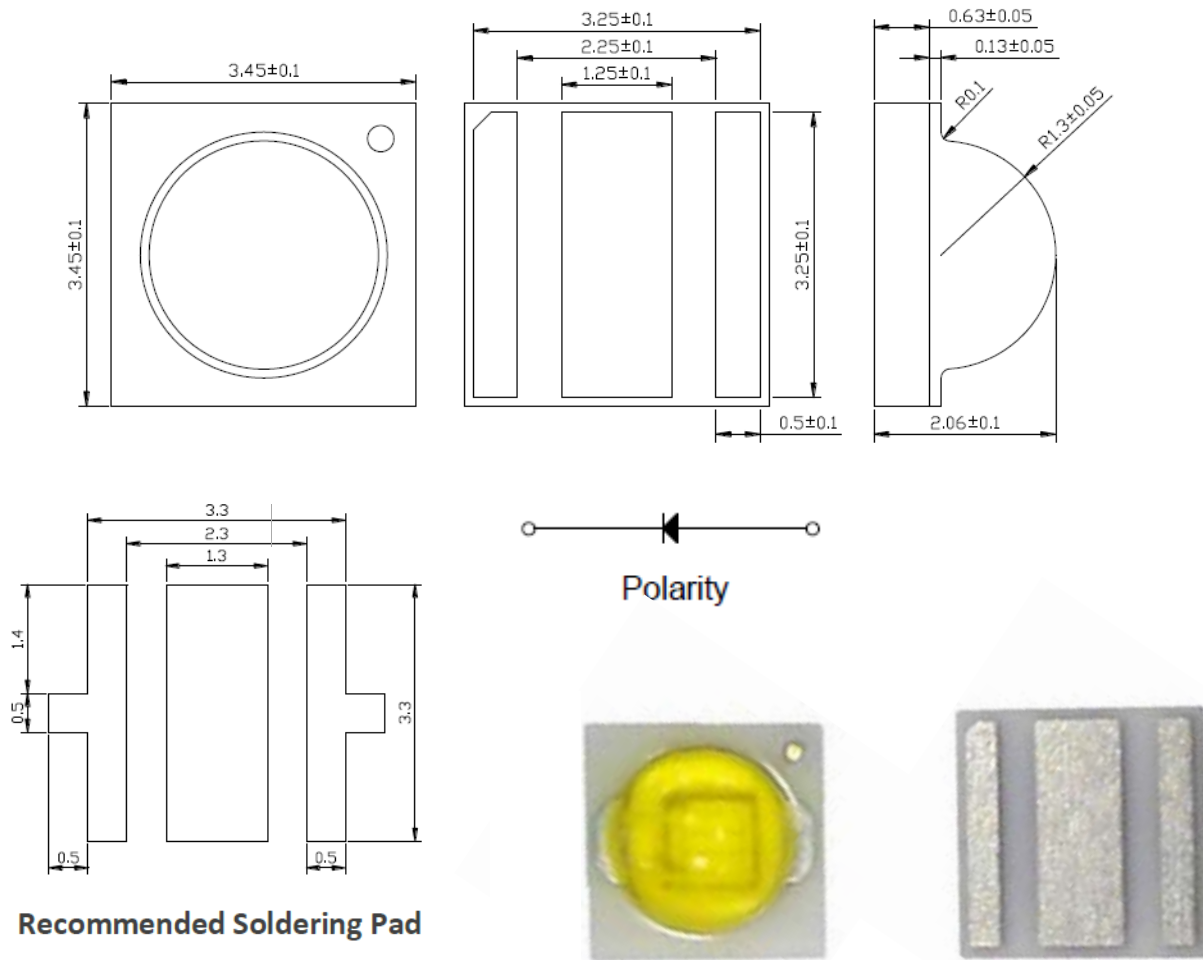


■ **Package Dimension:**



Recommended Soldering Pad

Part NO.	Chip	Emitting Color	Lens Color
AL-01CEW03WC-A2	InGaN	White	Yellow Diffused

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25\text{mm}$ (.010") unless otherwise noted.
3. Protruded resin under flange is 1.0mm(.04") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.
6. This data-sheet only valid for six months.

■ Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	MAX.	Unit
DC Forward Current	I _F	700	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	2.48	W
Pulse Forward Current	I _{FP}	1000	mA
LED junction Temperature (at 350mA)	T _j	125	°C
Thermal Resistance	R _{th}	10	K/W
Operating Temperature Range	Topr	-40°C to +100	°C
Storage Temperature Range	Tstg	-40°C to +100	°C
Manual Soldering Time at 260°C (Max.)	Tsol	5	seconds

Notes:

1. Maximum DC forward current is determined by the overall thermal resistance and ambient temperature.
2. I_{FP} conditions: pulse width $\leq 1\text{ms}$ and duty cycle $\leq 10\%$.

■ Electrical Optical Characteristics at Ta=25°C

Parameter	BIN	Symbol	Min.	Typ.	Max.	Unit	Test Condition			
Daylight	1L	Flux	---	195	---	lm	I _F =700mA			
	1M		---	205	---					
	1N		---	220	---					
	1P		---	240	---					
Neutral White	1I		---	155	---					
	1J		---	170	---					
	1L		---	195	---					
	1M		---	205	---					
Warm White	1G		---	120	---					
	1H		---	135	---					
	1I		---	155	---					
	1J		---	170	---					
	1K		---	195	---					
Forward Voltage			V _F	2.8	---			3.6	V	I _F =350mA
Daylight			CCT	5300	---			10000	K	I _F =350mA
Neutral White		3500		---	5300					
Warm White		2700		---	3500					
Emission Angle		2θ1/2	---	120	---	Deg	I _F =350mA			

Notes:

1. Luminous flux is measured with an accuracy of ±10%
2. The forward voltage is measured with an accuracy of ±0.1V

■ Characteristics Curves $T_J=25^\circ\text{C}$

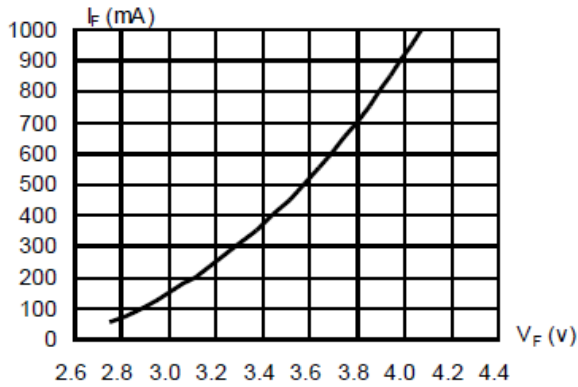


Fig.1 Forward Current vs. Forward Voltage

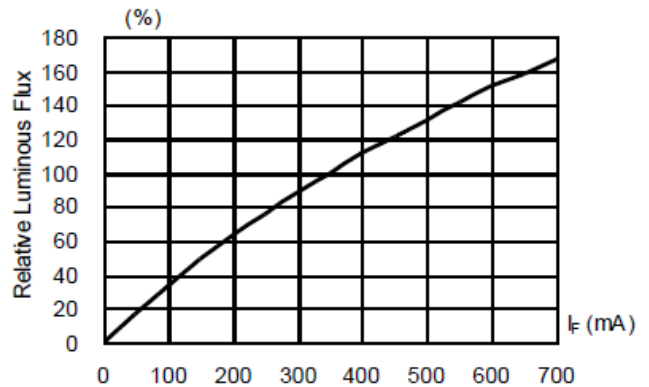


Fig.2 Luminous Flux vs. Forward Current

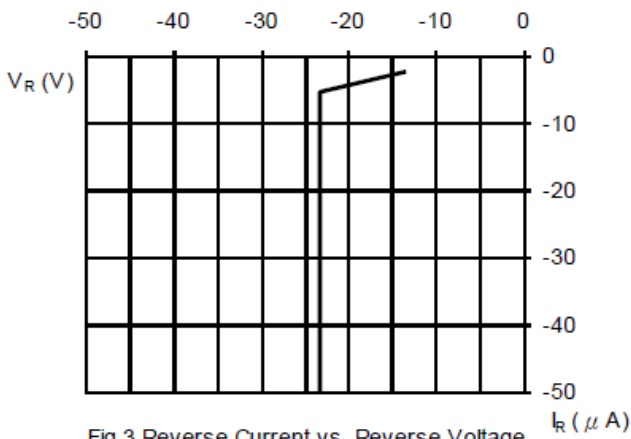


Fig.3 Reverse Current vs. Reverse Voltage

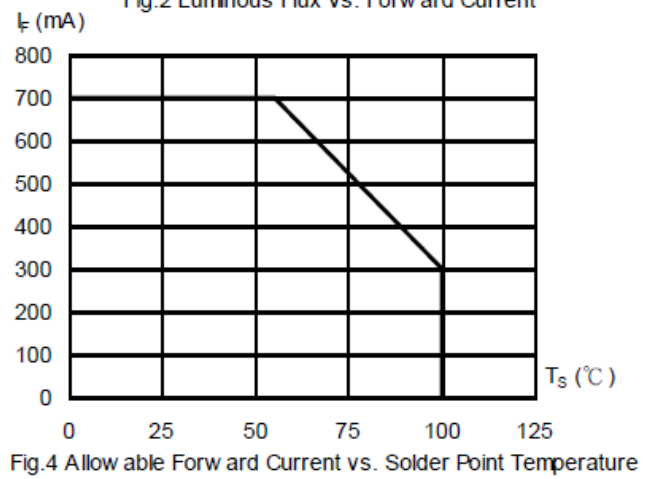


Fig.4 Allowable Forward Current vs. Solder Point Temperature

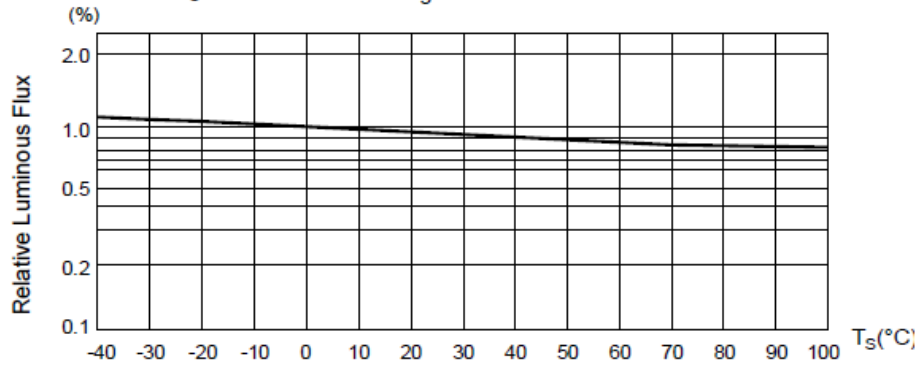


Fig.5 Luminous Flux at $I_F=350\text{mA}$ vs. Solder Point Temperature

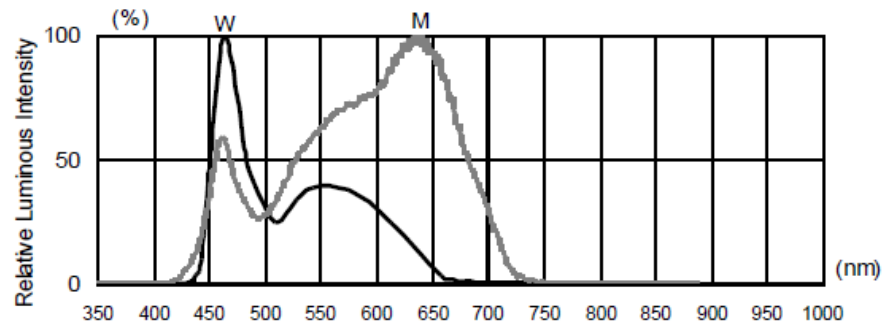
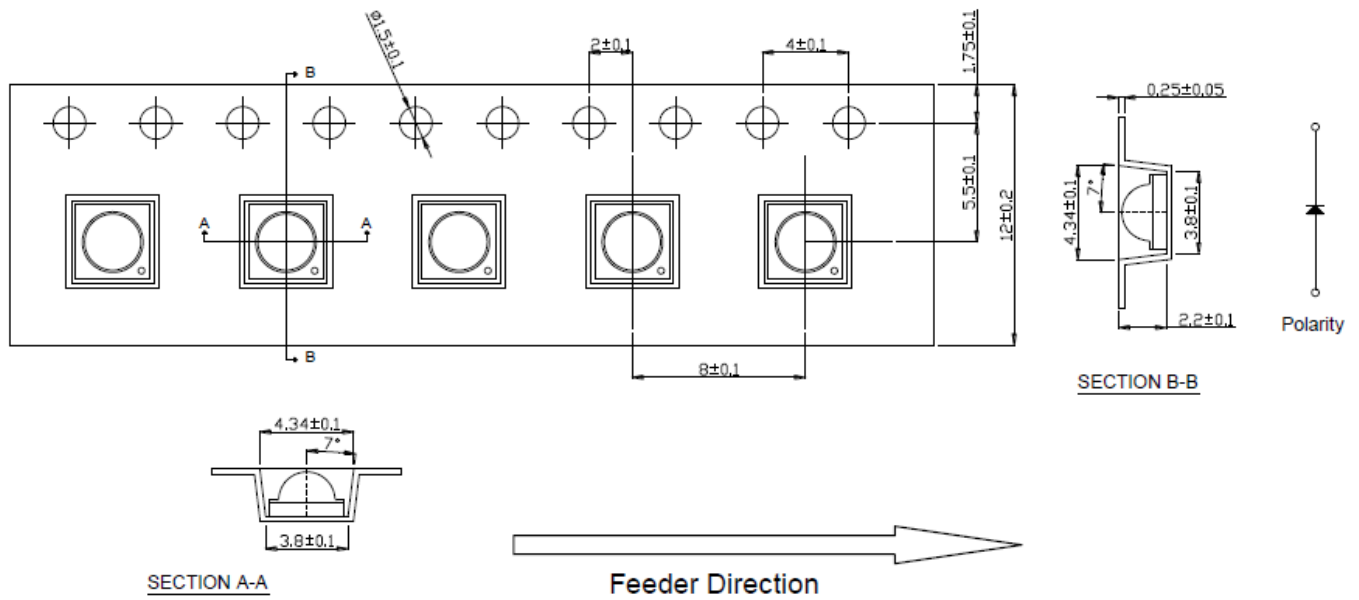


Fig.6. Relative Luminous Intensity vs. Wavelength

Packing Information



Notes:

1. All dimensions are in millimeter.
2. Tolerance is $\pm 0.10\text{mm}$ unless otherwise noted.